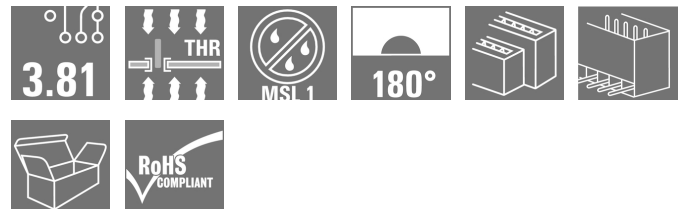


**OMNIMATE Signal - series BC/SC 3.81
SCD-THR 3.81/12/180G 1.5SN BK BX**

Weidmüller Interface GmbH & Co. KG
 Klingenbergstraße 16
 D-32758 Detmold
 Germany
 Fon: +49 5231 14-0
 Fax: +49 5231 14-292083
www.weidmueller.com

Product image


Similar to illustration

High-temperature-resistant two-tier SCD-THR pin header for reflow soldering.

- It allows you to use two interfaces on only one surface and with only one step in the work flow.
- Outlet direction: 90° (recumbent)
- Connections at the same level and with access that is flush over the front board.
- Space for labelling and coding
- Packed in cardboard box.

Weidmüller's 3.81-mm-pitch (0.15 inch) plug-in connectors are compatible with the layouts of standard connectors and offer space for labelling and coding.

General ordering data

Delivery status	Discontinued
Available until	2016-04-08
Type	SCD-THR 3.81/12/180G 1.5SN BK BX
Order No.	1031340000
Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.81 mm, No. of poles: 12, 180°, Solder pin length (l): 1.5 mm, tinned, Black, Box
GTIN (EAN)	4032248760374
Qty.	50 pc(s).
Product data	IEC: 320 V / 17.5 A UL: 300 V / 10 A
Packaging	Box

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Technical data

Dimensions and weights

Width	24.25 mm	Width (inches)	0.955 inch
Height	23.4 mm	Height (inches)	0.921 inch
Height of lowest version	21.9 mm	Depth	22.7 mm
Depth (inches)	0.894 inch	Net weight	10.362 g

System specifications

Product family	OMNIMATE Signal - series BC/SC 3.81	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.81 mm
Pitch in inches (P)	0.15 inch	Outgoing elbow	180°
No. of poles	12	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	+0,02 / -0,02 mm
Tolerance of solder pin position	± 0.1 mm	Solder pin dimensions	d = 1.0 mm, Octagonal
Solder pin dimensions = d tolerance	0 / -0,03 mm	Solder eyelet hole diameter (D)	1.3 mm
Solder eyelet hole diameter tolerance (D)+ 0,1 mm		Outside diameter of solder pad	2.1 mm
Template aperture diameter	1.9 mm	L1 in mm	19.05 mm
L1 in inches	0.75 inch	Number of rows	2
Pin series quantity	2	Touch-safe protection acc. to DIN VDE 57 106	Safe from finger touch
Touch-safe protection acc. to DIN VDE 0470	IP 20	Volume resistance	6.00 mΩ
Can be coded	Yes	Plugging cycles	25
Plugging force/pole, max.	8 N	Pulling force/pole, max.	5.5 N

Material data

Insulating material	LCP GF	Colour	Black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
CTI	≥ 175	Insulation resistance	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	Copper alloy	Contact surface	tinned
Storage temperature, min.	-25 °C	Storage temperature, max.	55 °C
Max. relative humidity during storage	80 %	Operating temperature, min.	-50 °C
Operating temperature, max.	120 °C	Temperature range, installation, min.	-25 °C
Temperature range, installation, max.	120 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. no. of poles (Tu=20°C)	17.5 A
Rated current, max. no. of poles (Tu=20°C)	9.4 A	Rated current, min. no. of poles (Tu=40°C)	17 A
Rated current, max. no. of poles (Tu=40°C)	8.1 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 76 A

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated current (Use group B / CSA)	11 A
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Technical data
Rated data acc. to UL 1059

Institute (cURus)



Certificate No. (cURus)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 10 A

Rated current (Use group D / UL 1059) 10 A

Reference to approval values

Specifications are
 maximum values, details -
 see approval certificate.

Packaging

Packaging	Box	VPE length	0
VPE width	0	VPE height	0

Classifications

ETIM 4.0	EC002637	ETIM 5.0	EC002637
eClass 6.2	27-26-07-04	eClass 7.1	27-44-04-02
eClass 8.1	27-44-04-02	eClass 9.0	27-44-04-02

Notes

Notes

- Rated current related to rated cross-section & min. No. of poles.
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- P on drawing = pitch

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Approvals

Approvals



ROHS

Conform

OMNIMATE Signal - series BC/SC 3.81 SCD-THR 3.81/12/180G 1.5SN BK BX

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Technical data

Downloads

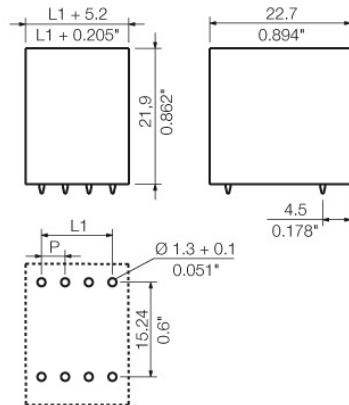
Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Brochure/Catalogue	FL DRIVES EN MB DEVICE MANUF. EN FL DRIVES DE CAT 2 PORTFOLIOGUIDE EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL INVERTER EN FL BASE STATION EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN
SMT white paper	Download Whitepaper

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Drawings

Dimensional drawing



Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

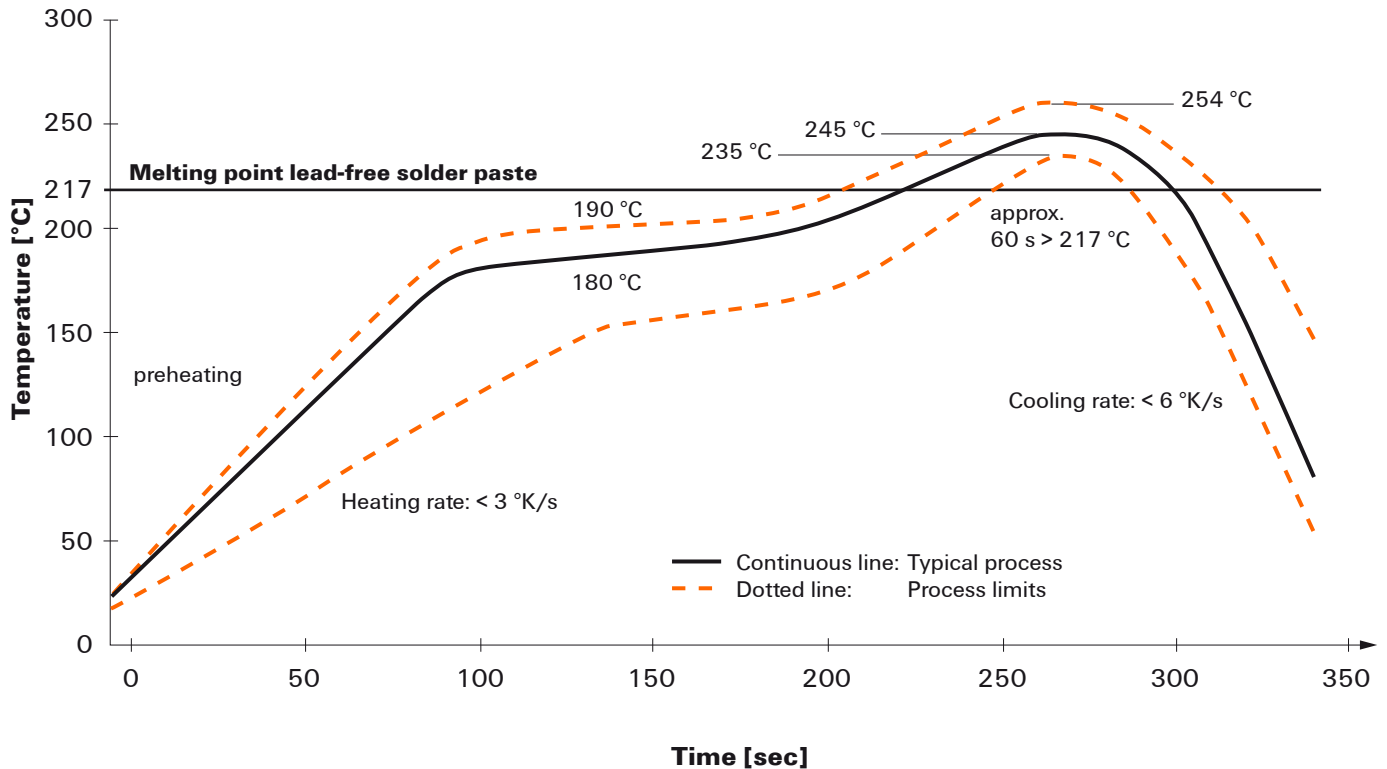
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.